



**THE DATASHEET OF
SD52-100-R**



SD52

High power density, low profile shielded power inductors



Product description

- Octagonal shape shielded drum core
- Inductance range from 1.2 uH to 150 uH
- Current range from 0.28 A to 3.14 A
- 5.6 mm x 5.2 mm footprint surface mount package in a 2.0 mm height
- Ferrite core material
- Halogen free, lead free, RoHS compliant

Applications

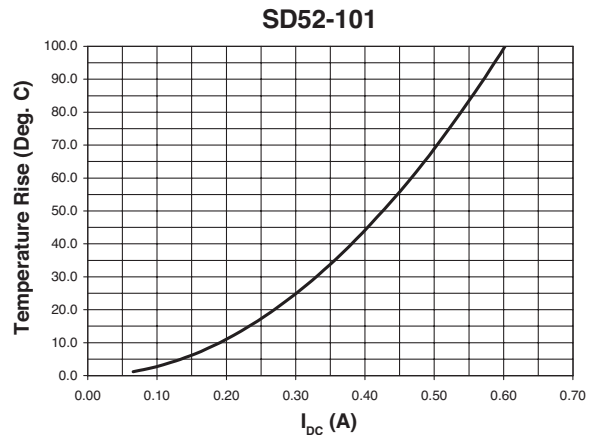
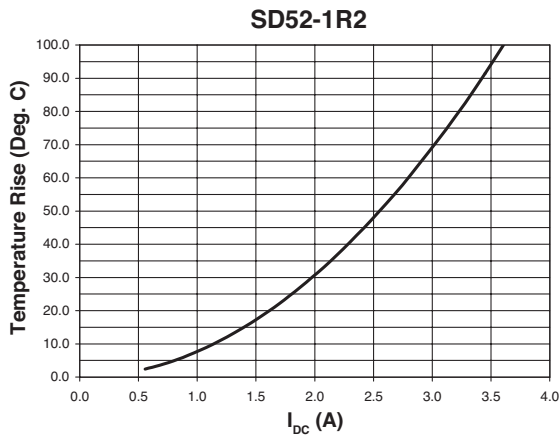
- Desktop computers
- Notebook and laptop regulators
- Graphics cards
- Digital cameras, media devices

Environmental Data

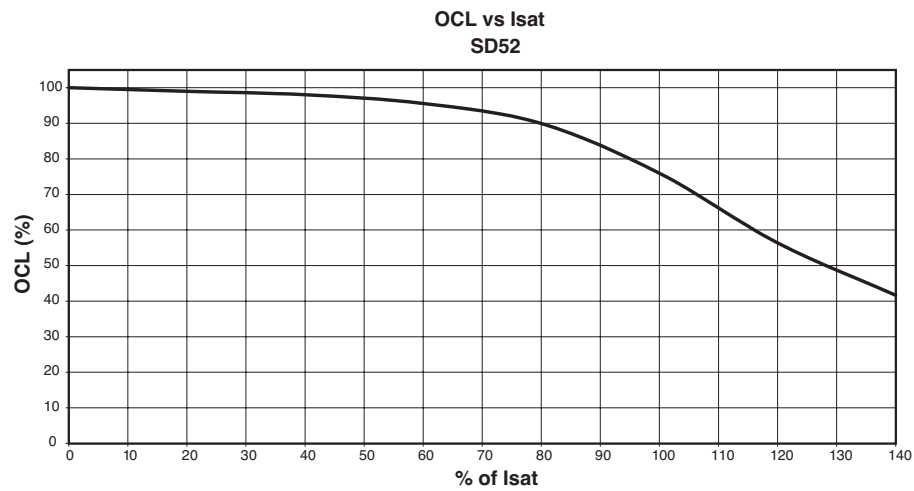
- Storage temperature range: -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise).
- Solder reflow temperature: J-STD-020D compliant



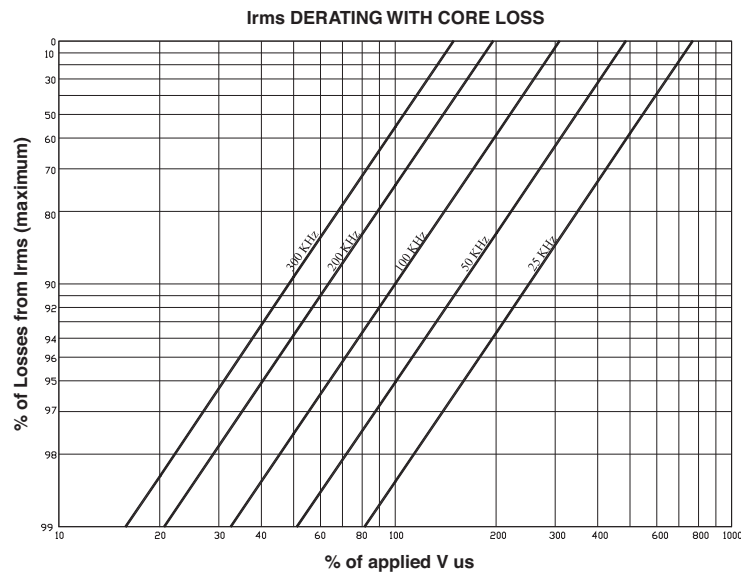
DC current vs. temperature



Inductance characteristics



Core loss



Solder reflow profile

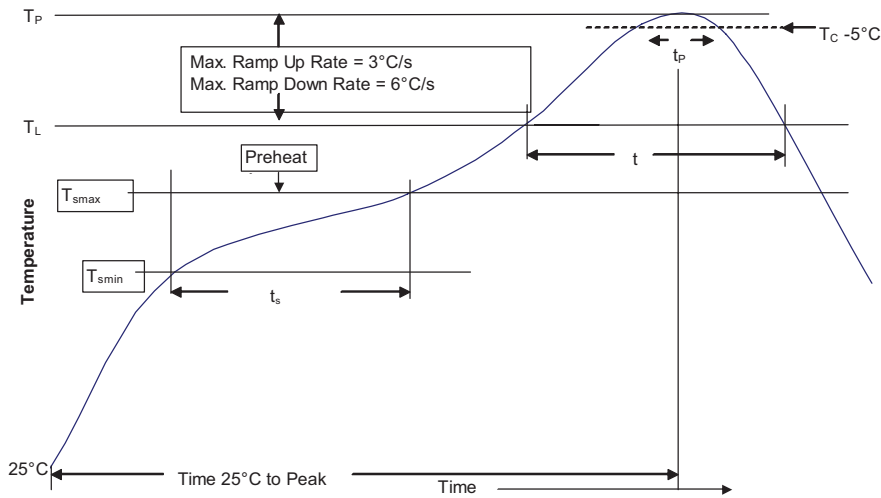


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T _{smin})	100°C	150°C
• Temperature max. (T _{smax})	150°C	200°C
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T _{smax} to T _p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T _L)	183°C	217°C
Time at liquidous (t _L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T _p)*	Table 1	Table 2
Time (t _p)** within 5 °C of the specified classification temperature (T _C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T _p to T _{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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Eaton
Electronics Division
1000 Eaton Boulevard
Cleveland, OH 44122
United States
www.eaton.com/elx

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